

Claims

1. (Currently Amended) A solid-state image pickup device comprising:
 - a circuit board having an opening;
 - a sensor package in which a chip of solid-state image pickup element with a light-receiving surface is placed, the sensor package disposed at one surface of the circuit board so that a the light-receiving surface of a the chip of solid-state image pickup element opposes the opening;
 - a seal adhered to the sensor package for sealing in the solid-state image pickup element; and
 - an optical unit disposed at the other surface of the circuit board so that incident light is focused on the light-receiving surface.
2. (Original) A solid-state image pickup device according to Claim 1, wherein the sensor package includes a signal processing circuit for processing a signal of the solid-state image pickup element.
3. (Original) A solid-state image pickup device according to Claim 1, wherein the solid-state image pickup element has a signal processing function.
4. (Original) A solid-state image pickup device according to Claim 1, wherein the circuit board is connected to an external device without a connector.
5. (Currently Amended) A method of producing a solid-state image pickup device comprising the steps of:
 - providing a circuit board with an opening;
 - joining a sensor package, in which a chip of solid-state image pickup element has been previously sealed, to one surface of the circuit board so that a light-receiving surface of the chip of solid-state image pickup element opposes the opening; and
 - disposing and joining an optical unit at and to the other surface of the circuit board so that incident light is focused on the light-receiving surface.
6. (Original) A method of producing a solid-state image pickup device according to Claim 5, wherein the sensor package includes a signal processing circuit for processing a signal of the solid-state image pickup element.
7. (Original) A method of producing a solid-state image pickup device according to Claim 5, wherein the solid-state image pickup element has a signal processing function.
8. (Original) A method of producing a solid-state image pickup device according to Claim 5, wherein the circuit board is connected to an external device

without a connector.

9. (Previously Presented) A solid-state image pickup device according to Claim 1, wherein the seal is a glass seal.